



PATENT 2827

Case Docket No. MICRON.110A

Date: January 23, 2003

Page 1

In re application of : Jiang  
App. No. : 09/471,071  
Filed : December 21, 1999  
For : DIE ATTACH MATERIAL  
FOR TBGA OR FLEXIBLE  
CIRCUITRY  
Examiner : Alcala, J.  
Art Unit : 2827

I hereby certify that this correspondence and all marked  
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2327, Arlington, VA 22202, on

January 23, 2003

(Date)

Lang J. McHardy, Reg. No. 50,591

UNITED STATES PATENT AND TRADEMARK OFFICE  
BOX NON-FEE AMENDMENT  
P.O. Box 2327  
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	20	—	20	= 0 ×	\$18	= \$0
Independent Claims	5	—	7	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add					\$280	= \$0
Time Extension Fee						\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$0

(X) Five sheets of replacement drawings.

(X) Return prepaid postcard.

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TC 2800 MAIL ROOM

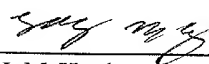
**PATENT**

Case Docket No. MICRON.110A

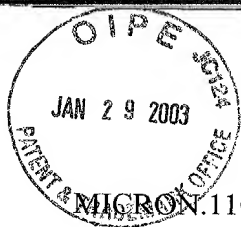
Date: January 23, 2003

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\_\_\_\_\_  
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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Tongbi Jiang ) Group Art Unit 2827  
Appl. No. : 09/471,071 )  
Filed : December 21, 1999 )  
For : DIE ATTACH MATERIAL )  
FOR TBGA OR FLEXIBLE )  
CIRCUITRY )  
Examiner : Jose Alcala )

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AMENDMENT

United States Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated October 23, 2002, please amend the above-identified application as indicated below.

IN THE CLAIMS:

**Please amend the claims as follows:**

8. An integrated circuit package, comprising:  
a die;  
a die attach layer over the die; and  
an array of solder balls over the die attach layer;  
wherein the die attach layer has a coefficient of thermal expansion of less than  
about 106 ppm/°C.